





OTHER

OPTION

-K

= (5.50 mm) .217" DIA

Polyimide film Pick & Place Pad

(N/A with -PC4)

-PC4

= 4 Power

Pins/End

(N/A with -A)

(0.635 mm) .025" PITCH • QMSS/QFSS SERIES

.125

QMSS Board Mates: QFSS

QFSS
Board Mates:

QMSS/QFSS Standoffs:

SO

SPECIFICATIONS

Insulator Material: Liquid Crystal Polymer Terminal, Ground Plane & Shield Material: Phosphor Bronze Plating: Au over 50 μ" (1.27 μm) Ni (Tin on Ground Plane Tail) Operating Temp Range: -55 °C to +125 °C Current Rating:

-55 °C to +125 °C Current Rating: Contact: 3.4 per pin (4 adjacent pins powered) Ground Plane: 7.8 A per ground plane (2 ground planes powered) Voltage Rating: 300 VAC/424 VDC

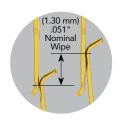
PROCESSING

Lead-Free Solderable:

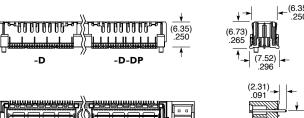
SMT Lead Coplanarity: (0.10 mm) .004" max (026-078)

Board Stacking:

For applications requiring more than two connectors contact ipg@samtec.com



PINS PER ROW NO. OF PAIRS **PLATING QMSS** 06.75 **TYPE** OPTION **-026, -052, -078** (52 total pins per bank / 40 signals + 12 grounds to shield = -D) -D = 10 μ" (0.25 μm) Gold on contact, = Single-Ended Matte Tin on tail -016, -032, -048 -D-DP (16 pairs per bank = -D-DP) = Differential Pair No. of Banks x (21.34) .840 - (0.51) .020 STATISTICAL PARTIES (3.18)

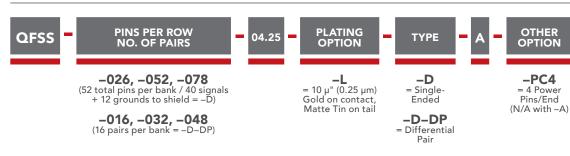


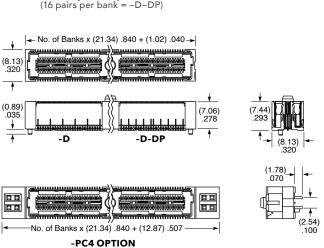
No. of Banks x (21.34) .840 + (13.21) .520 -

(6.35) PACKAGING OPTION Tape & Reel Options (-TR & -FR) available. Visit series web

(2.54) .100 Tape & Reel
Options
(-TR & -FR)
available. Visit
series web
page and view
engineering prints
for complete
specifications.

View complete specifications at: samtec.com?QMSS





PACKAGING OPTION

Tape & Reel
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(-TR & -FR)
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Note:

Some lengths, styles and options are non-standard, non-returnable.

View complete specifications at: samtec.com?QFSS